| Electronic Acknowledgement Receipt | | | | | |
|--------------------------------------|---|--|--|--|--|
| EFS ID: | 1998052 | | | | |
| Application Number: | 10596387 | | | | |
| International Application Number: | | | | | |
| Confirmation Number: | 5987 | | | | |
| Title of Invention: | EPOXY RESIN MOLDING MATERIAL FOR SEALING AND ELECTRONIC COMPONENT | | | | |
| First Named Inventor/Applicant Name: | Kazuyoshi Tendou | | | | |
| Customer Number: | 24203 | | | | |
| Filer: | Joerg-Uwe V. Szipl/Bridget Burke | | | | |
| Filer Authorized By: | Joerg-Uwe V. Szipl | | | | |
| Attorney Docket Number: | MIYOSH0006 | | | | |
| Receipt Date: | 23-JUL-2007 | | | | |
| Filing Date: | | | | | |
| Time Stamp: | 11:21:23 | | | | |
| Application Type: | U.S. National Stage under 35 USC 371 | | | | |

Payment information:

| Submitted with Payment | no |
|------------------------|----|
|------------------------|----|

File Listing:

| Document Number | Document Description | File Name | File Size(Bytes) /Message Digest | Multi Part /.zip | Pages (if appl.) |
|--------------------|----------------------------------|---------------------------------------|--|---------------------|---------------------|
| 1 1 | Information Disclosure Statement | 07-07-23_IDS_before_with_ cert.pdf | 76341 | - no | 3 |
| | (IDS) Filed | | f3e0d1d1ab24546d66fb428496a91c8a 401d66b0 | | |
| Warnings: | | | | | |

| Information: | : | | | | | |
|--|------------------------------------|--|---------|----|--|--|
| This is not an | USPTO supplied IDS fillable form | | | | | |
| 2 Information Disclosure Statement (IDS) Filed | Information Disclosure Statement | 07-07-23_US_IDS_FormS | 1053178 | | | |
| | B_08a.pdf | fdf325018653774ea4b4eb1f57cd12316 f96932d | no | 4 | | |
| Warnings: | | | | | | |
| Information: | : | | | | | |
| 3 Foreign Reference | FR01_KR2001-0074819.pdf | 1223212 | no | 22 | | |
| | | 5a1b3078e8364f739c70f869c4502d05 2b248736 | | | | |
| Warnings: | | | | | | |
| Information: | | | | | | |
| 4 NPL Documents | NPL01_Korean_Office_Actio n.pdf | 619323 | no | 13 | | |
| | | 23869ddb166092800872fa1fff078108d 60f9e73 | | | | |
| Warnings: | | | | | | |
| Information: | | | | | | |
| | | Total Files Size (in bytes) | 2972054 | | | |

This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.

New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

New International Application Filed with the USPTO as a Receiving Office

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.